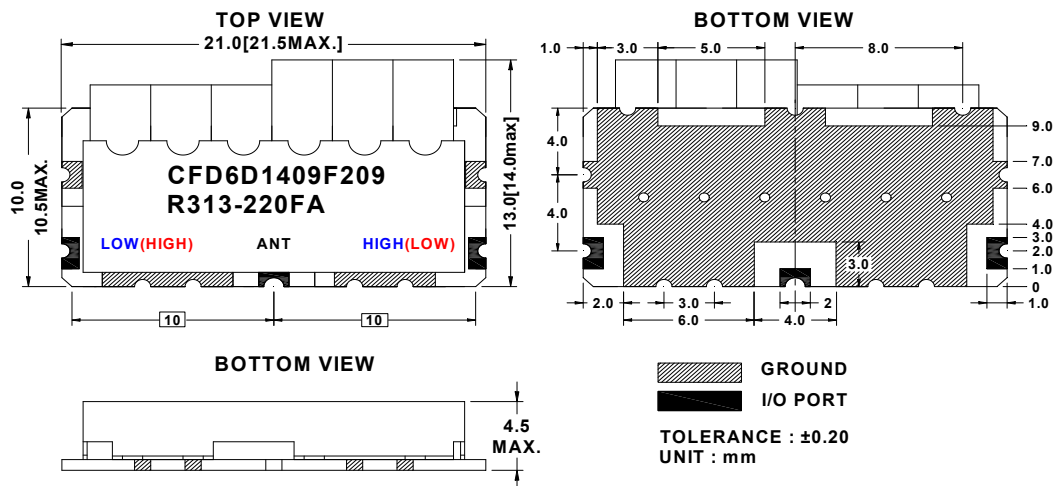


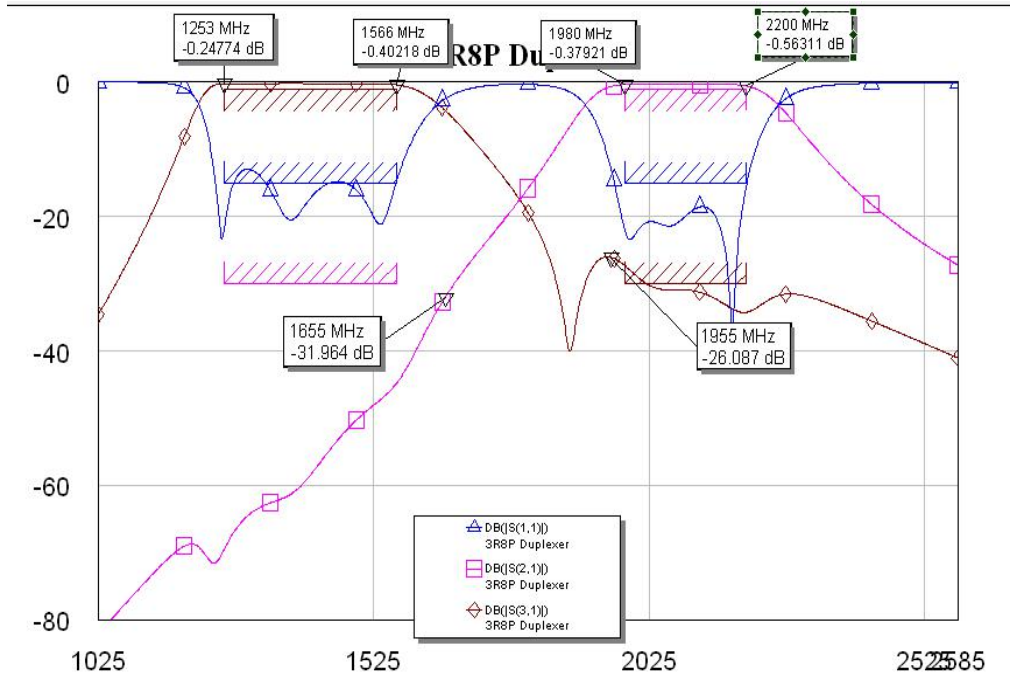
Electrical Specification

ITEMS	ANT >> Low	ANT >> High	UNIT
Center Frequency [fo]	1409.5	2090.0	MHz
Bandwidth [BW]	fo ±156.5 [1155.0~1285.0]	fo ±110.0 [1980.0~2200.0]	MHz
Insertion Loss in BW	1.5	1.5	dB max
Ripple in BW	1.0	1.0	dB max
Return Loss in BW	10.0	10.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	25 dBmin.@[1980.0~2200.0]	30 dBmin.@[1253~1566]	MHz
	dBmin. @ [~]	dBmin. @ [~]	MHz
	Bmin. @ [~]	Bmin. @ [~]	MHz
	dBmin. @ [~]	dBmin. @ [~]	MHz
Group Delay Variation			ns max
Input Power	3.0		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40°C to +85°C		

Mechanical Specification

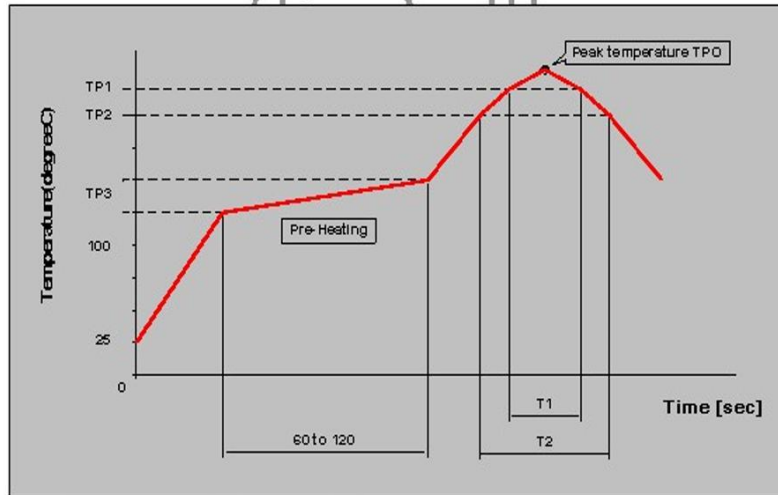


 Plot Data



 Recommended PC Board Pattern

 Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TP0 (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±/5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180